



Solder plus Support

REL61™

SOLDER ALLOY

Available in Paste, Wire and Bar



REL61 ALLOY AT A GLANCE

- ▶ Mitigates tin whisker formation
- ▶ Enhanced reliability versus SAC alloys
- ▶ Low cost SAC (Sn-Ag-Cu) alloy
- ▶ Improved thermal cycling performance
- ▶ Improved wetting versus all low/no-silver alloys

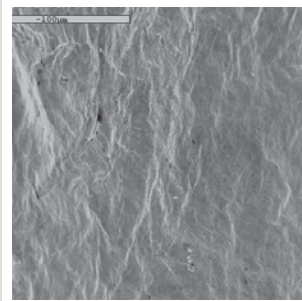


AIM, a leading global manufacturer of solder assembly materials for the electronics industry, introduces REL61, an enhanced reliability, low silver, lead-free solder alloy.

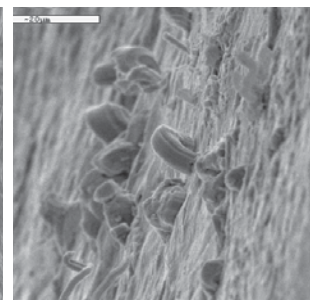
REL61 LEAD-FREE SOLDER ALLOY, developed by AIM, is comprised of tin, bismuth, silver, copper and elemental grain structure refiners. Extensive testing indicates REL61 can reduce tin whisker formation as well as outperforming SAC alloys in thermal shock, vibration and drop shock resistance. REL61 exhibits superior spread, flow and wetting when compared to low silver alloys in production testing. REL61 is ideally suited for industries which require increased durability in thermal cycling performance such as LED lighting, in-cabin automotive electronics and high power applications. REL61 provides the electronics assembly marketplace a low cost alternative to SAC alloys that has the reliability and performance characteristics equal to or greater than SAC305 and other low/no-silver solder alloys.

REL61™ TIN WHISKER GROWTH COMPARISON

@3100 HOURS



REL61 Alloy



SAC305